

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): A microwave package delimiting an interior volume, comprising at least:

[[-]] a Faraday cage formed by a conducting surface surrounding the interior volume,
[[-]] a connection point placed outside the Faraday cage, the connection point being intended to be linked electrically to an exterior circuit,

[[-]] an input-output passing through the Faraday cage and linked electrically to the connection point, and

[[-]] a base forming a face of the package, the exterior surface of the base forming a mounting surface intended to be applied to the exterior circuit, the connection point being placed on the mounting surface, so that the connection point is placed between the Faraday cage and the exterior circuit when the package is mounted on the exterior circuit.

2. (currently amended): The package as claimed in claim 1, ~~in which~~ wherein the connection point is linked to the input-output by a straight link, the link being perpendicular to the exterior circuit when the package is mounted on top.

3. (currently amended): The package as claimed in claim 1, ~~in which~~ wherein the connection point is formed by a conducting signal ball.

4. (currently amended): The package as claimed in claim 1, ~~whose~~ wherein the base is formed at least in part by an insulating material covering at least one conducting layer, the input-output being formed by a metallized hole passing through the insulating material.

5. (currently amended): The package as claimed in claim 1, ~~furthermore~~ comprising a coaxial structure shielding the connection point.

6. (currently amended): The package as claimed in claim[[s]] 5 ~~and 3~~, ~~in which~~ wherein the coaxial structure is formed by conducting earth balls, linked electrically to the Faraday cage, and placed around the signal ball.

7. (currently amended): The package as claimed in claim 6, ~~in which~~ wherein the earth balls placed around the signal ball are at least three in number.

8. (currently amended): The package as claimed in claim 7, ~~in which~~ wherein the earth balls are distributed around the signal ball over 360°.

9. (currently amended): The package as claimed in claim 1, ~~in which~~ wherein a component is placed in the interior volume of the package, the component being carried by a radiator forming a face of the package, the radiator being opposite the face carrying the mounting surface.

10. (original): A mounting comprising a package as claimed in claim 1 and a multilayer circuit, the package being mounted on the multilayer circuit, the multilayer circuit comprising at least one conducting earth plane, a metallized hole is made in the multilayer circuit opposite the connection point of the package, so as to convey the signal across the earth plane to a track of the circuit.

11. (currently amended): The mounting as claimed in claim[[s]] 10 ~~and 6~~, ~~in which~~ wherein the earth balls of the package are linked to at least one conducting earth plane of the multilayer circuit.

12. (original): The mounting as claimed in claim 10, comprising a second conducting earth plane, the two earth planes being on either side of the track.

13. (currently amended): The mounting as claimed in claim 10, ~~in which~~ wherein the conducting earth planes of the circuit are linked together by metallized holes.